

Thales, Radiall and Foxconn have initiated preliminary discussions on semiconductor production

Thales, Radiall and Foxconn announce they have initiated preliminary discussions to explore the potential creation, in France, of an industrial capacity in the field of outsourced semiconductor assembly and test (OSAT).

With a planned production capacity in excess of 100 million System In Package (SIP) per annum by 2031, this facility aims to address the European aerospace, automotive, telecoms and defense advanced packaging markets.

This initiative is expected to aggregate additional European industrial actors to sustain an investment in excess of €250m and ensure a strong European leadership for the project.

About Thales

Thales (Euronext Paris: HO) is a global leader in advanced technologies for the Defence, Aerospace, and Cyber & Digital sectors. Its portfolio of innovative products and services addresses several major challenges: sovereignty, security, sustainability and inclusion.

The Group invests more than €4 billion per year in Research & Development in key areas, particularly for critical environments, such as Artificial Intelligence, cybersecurity, quantum and cloud technologies.

Thales has more than 83,000 employees in 68 countries. In 2024, the Group generated sales of €20.6 billion.

Find the latest visuals of Thales and its Defence, Aerospace, and Cyber & Digital activities on the [Thales Media Library](#). For any specific requirements, please contact the Media Relations team.

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